




<b>PCN Number:</b>	20150511000	<b>PCN Date:</b>	05/14/2015
<b>Title:</b>	Qualification of NSE as Additional Assembly Site for Select VQFN package device		
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	08/14/2015	<b>Estimated Sample Availability:</b>	Date Provided at Sample request
<b>Change Type:</b>			
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
		<input type="checkbox"/>	Wafer Bump Site
		<input type="checkbox"/>	Wafer Bump Material
		<input type="checkbox"/>	Wafer Bump Process
		<input type="checkbox"/>	Wafer Fab Site
		<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Wafer Fab Process
<b>PCN Details</b>			
<b>Description of Change:</b>			
Qualification of NSE as Additional Assembly Site for Select VQFN package device. Assembly differences are shown in the following table:			
	<b>TI Clark</b>	<b>NSE</b>	
Mount Compound	4207123	PZ0031	
Wire	4218107 (0.8 Mil Cu)	GZ0017 (1.0 Mil Au)	
Lead finish	NiPdAu	NiPdAuAg	
<b>Reason for Change:</b>			
Continuity of Supply			
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>			
None			
<b>Changes to product identification resulting from this PCN:</b>			
Assembly Site			
TI Clark Philippines	Assembly Site Origin (22L)	ASO: QAB	
NSE Thailand	Assembly Site Origin (22L)	ASO: NSE	
Sample product shipping label (not actual product label)			
   <div style="display: flex; justify-content: space-between;"> <div style="border: 1px solid black; padding: 2px;">             MADE IN: Malaysia              2DC: 2d:              MSL 2 /260C/1 YEAR SEAL DT              MSL 1 /235C/UNLIM 03/29/04           </div> <div style="text-align: right;">             (1P) SN74LS07NSR              (Q) 2000 (D) 0336              (31T) LOT: 3959047MLA              (4W) TKY (1T) 7523483SI2              (P)              (2P) REV: (V) 0033317              (20L) CSO: SHE (21L) CCO: USA              (22L) ASO: MLA (23L) ACO: MYS           </div> </div> <p>LBL: 5A (L)T0:1750</p>			
ASSEMBLY SITE CODES: TI-Clark = I, NSE =J			
<b>Product Affected:</b>			
CC1101RGP	CC1101RGPR	CC1101RGPT	TLMW301RGPR

# Qualification Report

## Product Attributes

Attributes	Qual Device: CC1101RGP	Supporting QBS: TLV320AIC3254RHB	Supporting QBS: CC1101RGP
Assembly Site	UTAC/NSE	UTAC/NSE	UTAC/NSE
Package Family	QFN	QFN	QFN
Flammability Rating	UL 94 V-0	UL 94 V-0	UL94V-0
<b>Die Attributes</b>			
Wafer Fab Site	TSMC FAB 4	DMOS5	TSMC FAB 4
Wafer Fab Process	0.18UM-TSMC	1833C05	0.18UM-TSMC
<b>Package Attributes</b>			
Package Designator	RGP	RHB	RGP
Package Size (mils)	157.48 X 157.48	196.85 X 196.85	157.48 X 157.48
Body Thickness (mils)	39.37	35.43	39.37
Pin Count	20	32	20
Lead Frame Material	Cu	Cu	Cu
Lead Finish	NiPdAuAg	NiPdAu	NiPdAu
Mount Compound	PZ0031	PZ0031	PZ0031
Mold Compound	CZ0142	CZ0142	CZ0142
Green Status	Qualified Pb-free(SMT) and Green	Qualified Pb-free(SMT) and Green	Qualified Pb-free(SMT) and Green
Bond Wire Composition	Au	Au	Au
Bond Wire Diameter (mils)	1.0	1.0	1.0
Flammability Rating	UL 94 V-0	UL 94 V-0	UL94V-0

- QBS: Qual By Similarity

- Qual Device CC1101RGP is qualified at LEVEL3-260C

## Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: CC1101RGP	Supporting QBS: TLV320AIC3254RHB	Supporting QBS: CC1101RGP
AC	Autoclave	121C, 100%RH/96 hours	-	-	1/75/0
TC	Temperature Cycle	-65/150C/500 cycles	-	-	1/77/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	3/3/0	-	-
MSL	Moisture Sensitivity, JEDEC	Level 3-260C	3/36/0	1/12/0	-

- Preconditioning was performed for Autoclave, Temperature Cycle, as applicable

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>